

Filename: PMP30003RevA - BoM.xls
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PMP30003 REV A Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1, C2	2	22uF	GRM31CR71A226KE15L	MuRata	CAP, CERM, 22 μ F, 10 V, +/- 10%, X7R, 1206	1206
2	C101	1	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, COG/NP0, 0603	0603
3	J1, J2, J3, J4	4		5-146278-2	TE Connectivity	Header, 100mil, 2x1, Tin, TH	Header, 2x1, 100mil, TH
4	JP1, JP2	2		5-146278-3	TE Connectivity	Header, 100mil, 3x1, Tin, TH	Header, 3x1, 100mil, TH
5	L1	1	10uH	LPS4012-103MLB	Coilcraft	Inductor, Shielded Drum Core, Ferrite, 10 μ H, 0.75 A, 0.35 ohm, SMD	LPS4012
6	R3	1	18k	CRCW060318K0JNEA	Vishay-Dale	RES, 18 k, 5%, 0.1 W, 0603	0603
7	R4	1	2.0k	CRCW06032K00JNEA	Vishay-Dale	RES, 2.0 k, 5%, 0.1 W, 0603	0603
8	U1	1		TPS61029DRCR	Texas Instruments	Adjustable, 1.8-A Switch, 96% Efficient Boost Converter with Down-Mode, DRC0010J	DRC0010J

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